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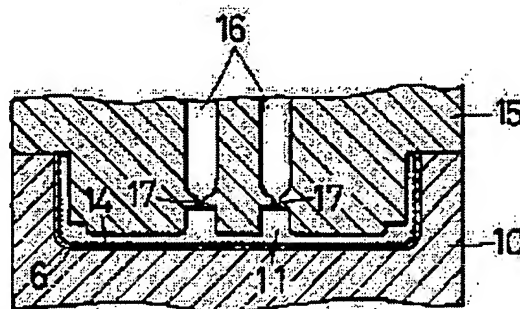
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(54) HOUSING FOR ELECTRONIC APPARATUS AND METHOD OF MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a housing for electronic apparatus combining the merits of metallic housing and synthetic resin housing and can be mass produced with high productivity in which the shape and structure can be designed freely.

SOLUTION: At least epoxy resin based paint is applied to a metal frame 6, cured and pretreated and then inserted into an injection molding die for injecting a rib 7. Surface of the metal frame 6 is filled with thermosetting synthetic resin by injection molding and the rib 7 is molded. The housing of a molded case cover 3 where the metal frame 6 and the thermosetting synthetic resin rib 7 are bonded integrally makes the most use of the features of metal in view points of strength and design of external view and the housing can have intricate internal shape and structure.



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